## CPC COOPERATIVE PATENT CLASSIFICATION

# PROCESSES FOR THE ELECTROLYTIC OR ELECTROPHORETIC PRODUCTION OF COATINGS

**ELECTROFORMING** (decorating textiles by metallising <u>D06Q 1/04</u>; manufacturing printed circuits by metal deposition <u>H05K 3/18</u>)

**APPARATUS THEREFOR** 

#### **WARNING**

The following IPC groups are not used in the CPC system. Subject matter covered by these groups is classified in the following CPC groups:  $\underline{C25D}$  5/24 covered by  $\underline{C25D}$  5/34  $\underline{C25D}$  5/26 covered by  $\underline{C25D}$  5/36  $\underline{C25D}$  5/38 covered by  $\underline{C25D}$  5/30 covered by  $\underline{C25D}$  5/42,  $\underline{C25D}$  5/44  $\underline{C25D}$  5/32 covered by  $\underline{C25D}$  5/46  $\underline{C25D}$  13/06 covered by  $\underline{C09D}$  5/44  $\underline{C25D}$  13/08 covered by  $\underline{C09D}$  5/448  $\underline{C25D}$  19/00 covered by  $\underline{C25D}$  17/00

### **Guide heading:**

C25D 1/00	Electroforming
C25D 1/003	. { 3D structures, e.g. superposed patterned layers }
C25D 1/006	. { Nanostructures, e.g. aluminum anodic oxidation templates [AAO] }
C25D 1/02	. Tubes Rings Hollow bodies
C25D 1/04	. Wires Strips Foils
C25D 1/06	. Wholly-metallic mirrors
C25D 1/08	Perforated or foraminous objects, e.g. sieves (C25D 1/10 takes precedence)
C25D 1/10	<ul> <li>Moulds         Masks         Masterforms {, e.g. mandrels, stampers }</li> </ul>
C25D 1/12	by electrophoresis { (electrophoretic coating <u>C25D 13/00</u> ) }
C25D 1/14	of inorganic material
C25D 1/16	Metals
C25D 1/18	of organic material
C25D 1/20	. Separation of the formed objects from the electrodes $\{$ with no destruction of said electrodes $\}$

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C25D 1/22
                            Separating compounds
C25D 3/00
                     Electroplating: Baths therefor
C25D 3/02
                        from solutions (C25D 5/24 to C25D 5/32 take precedence)
C25D 3/04
                            of chromium
C25D 3/06
                               from solutions of trivalent chromium
C25D 3/08
                               Deposition of black chromium { , e.g. hexavalent chromium, CrVI }
C25D 3/10
                               characterised by the organic bath constituents used
C25D 3/12
                            of nickel or cobalt { (C25D 3/56 takes precedence) }
C25D 3/14
                               from baths containing acetylenic or heterocyclic compounds
C25D 3/16
                                  Acetylenic compounds
C25D 3/18
                                  Heterocyclic compounds
C25D 3/20
                            of iron
C25D 3/22
                            of zinc
                      . .
C25D 3/24
                               from cyanide baths
                     . . .
C25D 3/26
                            of cadmium
                     . .
C25D 3/28
                               from cyanide baths
C25D 3/30
                            of tin
C25D 3/32
                               characterised by the organic bath constituents used
                     . . .
C25D 3/34
                            of lead
                      . .
C25D 3/36
                               characterised by the organic bath constituents used
                     . . .
C25D 3/38
                            of copper
C25D 3/40
                               from cyanide baths { , e.g. with Cu+ }
                      . . .
C25D 3/42
                            of light metals
                     . .
C25D 3/44
                               Aluminium
                      . . .
C25D 3/46
                            of silver
C25D 3/48
                            of gold
C25D 3/50
                            of platinum group metals
C25D 3/52
                               characterised by the organic bath constituents used
C25D 3/54
                            of metals not provided for in groups C25D 3/04 to C25D 3/50
C25D 3/56
                            of alloys
C25D 3/562
                               { containing more than 50% by weight of iron or nickel or cobalt { ; NiP, FeP,
                               CoP (Phosphatising C25D 11/36) } }
C25D 3/565
                               {containing more than 50% by weight of zinc }
C25D 3/567
                               {containing more than 50% by weight of platinum group metals }
                      . . .
C25D 3/58
                               containing more than 50% by weight of copper
C25D 3/60
                               containing more than 50% by weight of of tin {; SnP}
C25D 3/62
                               containing more than 50% by weight of gold
C25D 3/64
                               containing more than 50% by weight of silver
                      . . .
C25D 3/66
                        from melts
C25D 3/665
                            { from ionic liquids }
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## **WARNING**

Group C25D 3/665 is not complete, pending reorganization, see also C25D 3/66]

C25D 5/00	Electroplating characterised by the process Pretreatment or after-treatment of work-pieces
C25D 5/003	<ul> <li>{ Electroplating characterised by the use of gases, e.g. pressure influence (removal or gases or vapours, C25D 21/04) }</li> </ul>
	WARNING
	Groups <u>C25D 5/00B</u> , <u>C25D 5/006</u> are not complete, pending reorganization, see also <u>C25D 5/00</u>
C25D 5/006	• { Electroplating with applied electromagnetic field, not locally , e.g. for plating magnetic layers }
C25D 5/02	. Electroplating of selected surface areas
C25D 5/022	{ using masking means { (C25D 11/022 takes precedence) } }
C25D 5/024	{using locally applied electromagnetic radiation e.g. lasers }
C25D 5/026	{using locally applied jets of electrolyte }
C25D 5/028	{ one side electroplating {, e.g. substrate conveyed in a bath with inhibited background plating } }
C25D 5/04	Electroplating with moving electrodes
C25D 5/06	Brush or pad plating { (electrodes for pad plating C25D 17/14) }
C25D 5/08	<ul> <li>Electroplating with moving electrolyte {, characterised by electrolyte flow }, e.g. jet electroplating { (spraying of electrolyte on wires strip or foils <u>C25D 7/0642</u>, means or devices for moving the electrolyte <u>C25D 21/10</u>, <u>C25D 5/026</u> takes precedence) }</li> </ul>
C25D 5/10	<ul> <li>Electroplating with more than one layer of the same or of different metals (for bearings C25D 7/10)</li> </ul>
C25D 5/12	at least one layer being of nickel or chromium
C25D 5/14	two or more layers being of nickel or chromium, e.g. duplex or triplex layers
C25D 5/16	. Electroplating with layers of varying thickness {, e.g. rough surfaces } { ; Hull cells }
C25D 5/18	. Electroplating using modulated, pulsed or reversing current
C25D 5/20	. Electroplating using ultrasonics { , vibrations }
C25D 5/22	. Electroplating combined with mechanical treatment during the deposition
C25D 5/34	Pretreatment of metallic surfaces to be electroplated
C25D 5/36	of iron or steel

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C25D 5/38
                            of refractory metals or nickel
C25D 5/40
                               Nickel
                     . . .
                               Chromium
C25D 5/42
                            of light metals
C25D 5/44
                               Aluminium
C25D 5/46
                            of actinides
C25D 5/48
                        After-treatment of electroplated surfaces
C25D 5/50
                            by heat-treatment
C25D 5/505
                               {of electroplated tin coatings, e.g. by melting }
C25D 5/52
                            by brightening or burnishing
                     . .
C25D 5/54
                         Electroplating {on } non-metallic surfaces { ,e.g. on carbon or carbon composites }
                         (C25D 7/12 takes precedence)
C25D 5/56
                            on { thin or conductive } plastics { (coating metallic material C23C) }
C25D 7/00
                     Electroplating characterised by the article coated
C25D 7/001
                        { Magnets }
                         WARNING
                              Groups C25D 7/00B-C25D 7/008 are not complete, pending reorganization, see
                              also C25D 7/00
C25D 7/003
                        { Threaded pieces, e.g. bolts, nuts }
C25D 7/005
                        { Jewels or clockworks }
C25D 7/006
                        { Nanoparticles }
C25D 7/008
                        { Thermal barrier coatings }
C25D 7/02
                         Slide fasteners
C25D 7/04
                         Tubes
                         Rings
                         Hollow bodies
C25D 7/06
                         Wires
                         Strips
                         Foils
C25D 7/0607
                            {Wires }
C25D 7/0614
                            {Strips or foils }
C25D 7/0621
                               {In horizontal cells }
C25D 7/0628
                               {In vertical cells }
                      . . .
C25D 7/0635
                               {In radial cells }
                      . . .
C25D 7/0642
                               {Anodes }
                      . . .
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C25D 7/065
                               {Diaphragms }
                     . . .
C25D 7/0657
                               {Conducting rolls }
                     . . .
C25D 7/0664
                               {Isolating rolls }
C25D 7/0671
                               {Selective plating }
C25D 7/0678
                                  {using masks }
C25D 7/0685
                               {Spraying of electrolyte }
C25D 7/0692
                               {Regulating the thickness of the coating }
C25D 7/08
                        Mirrors
                         Reflectors
C25D 7/10
                        Bearings
C25D 7/12
                        Semiconductors { without seed layer }
C25D 7/123
                            { Semiconductors first coated with a seed layer for filling vias }
                            WARNING
                                 Groups C25D 7/12B-C25D 7/126 are not complete, pending reorganization,
                                 see also C25D 7/12]
C25D 7/126
                            { Semiconductors first coated with a seed layer for solar cells }
C25D 9/00
                     Electrolytic coating other than with metals (C25D 11/00, C25D 15/00 take
                     precedence; electrophoretic coating C25D 13/00)
C25D 9/02
                        with organic materials
C25D 9/04
                        with inorganic materials
C25D 9/06
                            by anodic processes
C25D 9/08
                            by cathodic processes
C25D 9/10
                               on iron or steel
C25D 9/12
                               on light metals
C25D 11/00
                     Electrolytic coating by surface reaction, i.e. forming conversion layers
C25D 11/005
                        { Apparatus specially adapted for electrolytic conversion coating (apparatus in general
                         for electrolytic coating C25D 17/00) }
                        WARNING
                              Groups C25B 11/00B, C25D 11/022-C25D 11/02F, C25D 11/045 are not
                              complete, pending reorganization, see also C25D 11/00
C25D 11/02
                        Anodisation
C25D 11/022
                            { Anodisation on selected surface areas }
C25D 11/024
                            {Anodisation under pulsed or modulated current or potential }
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C25D 11/026
                            { Anodisation with spark discharge [ANOF] }
C25D 11/028
                            { Borodising,, i.e. borides formed electrochemically }
                      . .
C25D 11/04
                            of aluminium or alloys based thereon
C25D 11/045
                               { for forming AAO templates }
C25D 11/06
                               characterised by the electrolytes used
C25D 11/08
                                  containing inorganic acids
C25D 11/10
                                  containing organic acids
C25D 11/12
                               Anodising more than once, e.g. in different baths
C25D 11/14
                               Producing integrally coloured layers
C25D 11/16
                               Pretreatment {, e.g. desmutting }
                      . . .
C25D 11/18
                               After-treatment, e.g. pore sealing (lacquering <u>B44D</u>)
C25D 11/20
                                  Electrolytic after-treatment
                      . . . .
C25D 11/22
                                     for colouring layers
C25D 11/24
                                  Chemical after-treatment
C25D 11/243
                                     {using organic dyestuffs }
                      _ _ _ _ _
C25D 11/246
                                     {for sealing layers }
                      . . . . .
C25D 11/26
                            of refractory metals or alloys based thereon
C25D 11/28
                            of actinides or alloys based thereon
C25D 11/30
                            of magnesium or alloys based thereon
                      . .
C25D 11/32
                            of semiconducting materials
                      . .
C25D 11/34
                            of metals or alloys not provided for in groups C25D 11/04 to C25D 11/32
                         Phosphatising {, e.g. NiP, CoP, FeP (bath solutions of NiP, CoP, FeP C25D 3/562) }
C25D 11/36
C25D 11/38
                         Chromatising
C25D 13/00
                      Electrophoretic coating (C25D 15/00 takes precedence; apparatus for continuously
                      conveying articles into baths B65G, e.g. B65G 49/00)
C25D 13/02
                         with inorganic material
C25D 13/04
                         with organic material
C25D 13/06
                            with polymers {not used, see C09D 5/44 }
C25D 13/08
                               by polymerisation in situ of monomeric materials (not used, see C09D 5/4476)
                      . . .
C25D 13/10
                         characterised by the additives used {not used, see C09D 5/448 }
C25D 13/12
                         characterised by the article coated
C25D 13/14
                            Tubes
                      . .
                            Rings
                            Hollow bodies
C25D 13/16
                            Wires
                            Strips
                            Foils
C25D 13/18
                         using modulated, pulsed, or reversing current
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C25D 13/20	. Pre-treatment
C25D 13/22	Servicing or operating { apparatus or multistep processes }
C25D 13/24	Regeneration of process liquids
0200 10/21	11 Regeneration of process liquids
C25D 15/00	Electrolytic or electrophoretic production of coatings containing { uncharged } embedded materials, e.g. particles, whiskers, wires
C25D 15/02	. Combined electrolytic and electrophoretic processes { with charged materials }
C25D 17/00	Constructional parts, or assemblies thereof, of cells for electrolytic coating (apparatus for continuously conveying articles into baths B65G, e.g. B65G 49/00; electric devices see the relevant classes, e.g. H01B, H02G) { (C25D 7/06, C25D 11/42, C25D 13/22, C25 takes precedence) }
C25D 17/001	• { Apparatus specially adapted for plating wafers, e.g. semiconductors, solar cells }
	WARNING
	Groups <u>C25B 17/00</u> B- <u>C25D 17/008</u> are not complete, pending reorganization, see also <u>C25D 17/00</u>
C25D 17/002	. { Cell separation, e.g. membranes, diaphragms }
C25D 17/004	. { Sealing devices }
C25D 17/005	. { Contacting devices }
C25D 17/007	. { Current conducting devices }
C25D 17/008	. { Current insulating devices }
C25D 17/02	Tanks     Installations therefor
C25D 17/04	External supporting frames or structures
C25D 17/06	. Suspending or supporting devices for articles to be coated
C25D 17/08	{ Supporting } racks { i.e. not for suspending }
C25D 17/10	• Electrodes { e.g. composition, counter electrode }
C25D 17/12	Shape or form (C25D 17/14 takes precedence)
C25D 17/14	for pad-plating
C25D 17/16	Apparatus for electrolytic coating of small objects in bulk
C25D 17/18	having closed containers
C25D 17/20	Horizontal barrels
C25D 17/22	having open containers
C25D 17/24	Oblique barrels

C25D 17/26	Oscillating baskets
C25D 17/28	<ul> <li>with means for moving the objects individually through the apparatus during treatment</li> </ul>
C25D 21/00	Processes for servicing or operating cells for electrolytic coating
C25D 21/02	. Heating or cooling
C25D 21/04	. Removal of gases or vapours $\{$ ; gas or pressure control (electroplating characterized by the use of gases $\underline{\text{C25D 5/003}}$ ) $\}$
C25D 21/06	. Filtering { particles other than ions (filtering ions C25D 21/22) }
C25D 21/08	. Rinsing
C25D 21/10	Agitating of electrolytes     Moving of racks
C25D 21/11	. Use of protective surface layers on electrolytic baths
C25D 21/12	<ul> <li>Process control or regulation (controlling or regulating in general G05)</li> </ul>
C25D 21/14	Controlled addition of electrolyte components
C25D 21/16	<ul> <li>Regeneration of process solutions { (C25D 13/24 takes precedence) }</li> </ul>
C25D 21/18	of electrolytes ( <u>C25D 21/22</u> takes precedence)
C25D 21/20	of rinse-solutions ( <u>C25D 21/22</u> takes precedence)
C25D 21/22	by ion-exchange